# Ariel Slepyan

#### **Contact Information**

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Education

08/2021 -PhD in Electrical and Computer Engineering

> Johns Hopkins University Baltimore, MD, USA

Advisor: Professor Nitish Thakor

Thesis: "Ultra Scalable Tactile Arrays without Taxel Electronics"

08/2020 - 08/2021M.S.E in Biomedical Engineering

> Johns Hopkins University Baltimore, MD, USA

Advisor: Professor Nitish Thakor Dean's Master's Fellowship

Thesis: "Scalable Tactile Sensing E-Skins Through Spatial Frequency

Encodina"

08/2016 - 05/2020B.S. in Biomedical Engineering

> Johns Hopkins University Baltimore, MD, USA

Bloomberg Scholarship

**Experience** 

Graduate Student 06/2020 -

Neuroengineering & Biomedical Instrumentation Lab

Johns Hopkins University Baltimore, MD, USA

--Focusing on scalable touch sensing in robotics

01/2024 -Co-Founder

> **Evoked Haptics** Baltimore, MD, USA

--Scalable touch sensors and wearable neural stimulators

01/2023 -Lead Hardware Engineer

> CurveAssure Spine Baltimore, MD, USA

--Leading hardware development of a wearable spine monitor

Summer 2019 Summer Researcher

> Singapore Institute for Neurotechnology Singapore

--Developed RFID-based wireless touch sensors

Summer 2018 Visiting Scholar

> Interuniversity Microelectronics Centre (IMEC) Leuven, Belgium

--Built microfluidic droplet sorter using DEP in silicon

01/2017 - 01/2019Undergraduate Researcher

BioMEMS Lab

Johns Hopkins University Baltimore, MD, USA --Built microfluidic droplet-based platform for measuring enzyme kinetics

Summer 2014/15 Research Intern

Groisman Lab

University of California, San Diego La Jolla, CA, USA

--Build PDMS chip to investigate thermotaxis of E. coli

**Awards & Honors** 

2024 Winner of JHU Fuel Cohort Prize (\$5k + \$3k)

Winner of WSE Excellence in Teaching, Advising, and Mentoring Award 2024 Invitee to JHU Fuel Accelerator (Evoked Haptics, 10/50 university-wide) 2024

2023 Winner of JHU President's Venture Fellowship (\$100,000 – CurveAssure)

2023	Grand Prize Winner of JHU Makerspace Design Challenge
2023	Finalist for IEEE World Haptics Student Innovation Challenge (P1)
2022	Invitee to the Telluride Neuromorphic Cognition Engineering Workshop (1 of 30 international)
2022	Grand Prize Winner of Johns Hopkins ECE Design Day
2022	Finalist in Johns Hopkins Healthcare Design Competition (\$5,000)
2021	Winner of Johns Hopkins Ignite Grant (\$1,000)
2020	Recipient of Dean's Master's Fellowship (1/2 Tuition Scholarship)
2019	Finalist for FastForward Summer Award (\$10,000)
2018	Winner of Johns Hopkins Spark Grant (\$1,000)
2017	2 <sup>nd</sup> place overall winner at MedHacks 2017
2017	Winner of Wolfram Award and Contrary Capital Prize at MedHacks 2017
2016	Recipient of Michael R. Bloomberg Scholarship (Full Tuition 4-year Scholarship)
2016	2 <sup>nd</sup> place in Microbiology at Intel ISEF 2016 (International Science and Engineering Fair)
2016	1 <sup>st</sup> place in Engineering at the New York State Science and Engineering Fair
2015	1st place in Materials Science at the New York State Science and Engineering Fair

## **Research Grants Awarded**

- TEDCO MII Technology Assessment Award 2024 (\$115,000) "High-Density Tactile Sensor Array with a Single Output Wire for Medical Rehabilitation". (#1 score in cohort 4.167 / 5)
- Space@Hopkins Seed Grant Program 2022 (\$25,000) "Self-Powered, Electronics-Free Tactile Sensors Immune to the Hazards of Cosmic Radiation"

#### **Patents and Invention Disclosures**

- 1. "SCALABLE DISTRIBUTED TACTILE SENSORS WITHOUT INTEGRATED CIRCUITS USING RESONANCE MULTIPLEXED PIEZOELECTRIC SENSORS" (JHU Tech ID #C18042)
- 2. "METHOD AND APPARATUS OF A HIGH-DENSITY NON-INVASIVE NEURAL STIMULATOR" (JHU Tech ID #C18182)

Provisional Patent Application Number = 63/655,671

3. "METHOD OF SCALABLE SENSOR ARRAYS THROUGH ROW COLUMN COMPRESSIVE SENSING" (JHU Tech ID #C18041)

Provisional Patent Application Number = 63/653,517

4. "SCALABLE, EVENT-BASED SENSING USING WIRELESS SENSOR ELEMENTS EMBEDDED IN FLEXIBLE ELASTOMER" (JHU Tech ID #C16118)

Patent Number = 18/553,717, Published 2022-10-06 https://patents.google.com/patent/WO2022212730A1 https://jhu.technologypublisher.com/technology/52625

#### **Teaching Lead of Original Courses**

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EN.520.299	PCB Design and Microcontroller Programming	Winter 2023, 2024
	Student feedback – "Arik is extremely helpful, and willin	g to put in the extra time
	for both students who are struggling and those who wai	nt to go above and
	beyond. 10/10 instructor!"	
EN.580.113	Prosthesis Instrumentation	Winter 2023
	HUB Article - https://hub.jhu.edu/2023/02/06/intersession	on-prosthesis-

Teaching Assistantships (14 classes)

	1.0.1p. ( <u>1.1.0.1</u> )	
EN.520.448	Advanced Electronics Design Lab	Spring 2023 – 2024
EN.580.571	Honors Instrumentation	Spring 2021 – 2024
EN.580.456	Introduction to Rehabilitation Engineering	Fall 2022 - 2023
EN.580.471	Principles of the Design of Biomedical Instrumentation	Fall 2020 - 2023
n/a	BME Design Studio TA	2021 – 2022
EN.580.457	Rehabilitation Engineering: Design Lab	Spring 2021
EN.580.477	Biomedical Data Science Lab	Fall 2019

#### **Leadership Experience**

2023 – Co-President of ECE Graduate Student Association

instrumentation/

## Student Mentorship (28 students)

<u>Master's Students:</u> Junjun Chen (2024 – ), Priyanka Fernandes (2023 – ), Tianao Li (2023 – ), Siddharth Krishnan (2022 – 2023), Michael Zakariaie (2022 – 2023), Arnab Chatterjee (2022), Yucheng "Jacky" Tian (2022)

<u>Undergraduate Students:</u> Rudy Zhang (2024 – ), Amanda Butler (2024 – ), Mathew Schricker (2023 – ), Laura Xing (2023 – ), Yanisa "Belle" Angkanapiwat (2022 – ), Guangyan "Molly" Li (2022 – 2023), Eli Levenshus (2021 – 2023), Aidan Aug (2021 – 2023), Dylan Zhu (2022 – 2023), Neeti Prasad (2022), Aryaman Shodhan (2021), Martin Prados de Haro (2021)

<u>High School Students</u>: El Donald (2024), Srinitha Kondapaneni (2023), Ian Tran (2023), Upanshu Bajaj, Shriya Sane, and Kimaya Basu (2022 – 2023), Pratham Mathapati, Pranavaa Elangovan, Sahil Mada (2020 – 2021),

# **Research Papers**

- 1. **A. Slepyan**, J. Chen, and N. Thakor "Scalable Tactile Sensing Skins: Sensors, Wiring and Data Management" Proceedings of the IEEE. 2024. *Under Review*.
- 2. **A. Slepyan**, M. Zakariaie, and N. Thakor "Sparsifying Tactile Data by Wavelet Transform" IEEE Sensors. 2024. *Under Review*.
- 3. S. Wang, K. Quinn, **A. Slepyan**, et al, "Channel selection and wavelet transformation-based data compression preserve motor unit information" 2024 46th Annual International Conference of the IEEE Engineering in Medicine and Biology Society (EMBC). 2024.
- 4. **A. Slepyan**, S. Krishnan, T. Li and N. Thakor, "A Multi-Channel, Low-Voltage, High-Frequency Programmable Electrical Stimulator for Sensory Feedback," 2023 IEEE Biomedical Circuits and Systems Conference (BioCAS), 2023. https://ieeexplore.ieee.org/document/10388769
- 5. Z. Ou, Y. Guo, P. Gharibani, **A. Slepyan**, et al "Time-frequency analysis of somatosensory evoked high-frequency (600 Hz) oscillations as an early indicator of arousal recovery after hypoxic-ischemic brain injury" Brain Sciences. 2022. https://www.mdpi.com/2076-3425/13/1/2
- 6. Y. Tian, **A. Slepyan**, et al, "Real-Time, Dynamic Sensory Feedback Using Neuromorphic Tactile Signals and Transcutaneous Electrical Nerve Stimulation" 2022 IEEE Biomedical Circuits and Systems Conference (BioCAS), 2022. <a href="https://ieeexplore.ieee.org/document/9948609">https://ieeexplore.ieee.org/document/9948609</a>
- 7. S. Sankar, **A. Slepyan**, et al, "Flexible Multilayer Tactile Sensor on a Soft Robotic Fingertip" 2022 IEEE Sensors, 2022. https://ieeexplore.ieee.org/document/9967059
- 8. A. Aug, **A. Slepyan**, E. Levenshus, N. Thakor, "Haptic Touch: A retrofittable tactile sensing glove and haptic feedback armband for scalable and robust tactile sensory feedback", 2022 9th IEEE International Conference on Biomedical Robotics and Biomechatronics (BioRob), Seoul, Korea, 2022. <a href="https://ieeexplore.ieee.org/document/9925475">https://ieeexplore.ieee.org/document/9925475</a>
- 9. **A. Slepyan**, S. Sankar, and N. Thakor, "Texture Discrimination Using a Neuromimetic Asynchronous Flexible Tactile Sensor Array with Spatial Frequency Encoding", 10th International IEEE/EMBS Conference on Neural Engineering, 2021 <a href="https://ieeexplore.ieee.org/document/9441136">https://ieeexplore.ieee.org/document/9441136</a>
- A. Slepyan and N. Thakor, "Towards scalable soft e-skin: Flexible event-based tactile-sensors using wireless sensor elements embedded in soft elastomer", 2020 8th IEEE International Conference on Biomedical Robotics and Biomechatronics (BioRob), New York, 2020 <a href="https://ieeexplore.ieee.org/document/9224353">https://ieeexplore.ieee.org/document/9224353</a>

### Conference and Abstract Presentations, unpublished

- 1. **A. Slepyan**, M. Iskarous, S. Sankar, and N. Thakor, "Scalable, Biomimetic Sensory Solutions for Dexterous Robotics Hands" 2021 NRI & FRR Principal Investigators' Meeting, 2021
- 2. **A. Slepyan**, R. Acharya, A. Silva, D. Kumar, and N. Thakor, "A Biomimetic Soft Finger for Palpation Applications", Do Good Robotics Symposium, Maryland, 2019
- 3. **A. Slepyan**, N. Ribeiro, A. Saad-Eldin, A. Blakney, "Rapid development of paper-based microfluidic devices using crayons and coffee filters", Baltimore Innovation Week Science Conference, 2017

#### **Professional Activities**

 Reviewer for 2024 10th IEEE International Conference on Biomedical Robotics and Biomechatronics (BioRob)

- Reviewer for 2022 29th IEEE International Conference on Electronics, Circuits & Systems Reviewer for 2022 9th IEEE International Conference on Biomedical Robotics and Biomechatronics (BioRob)